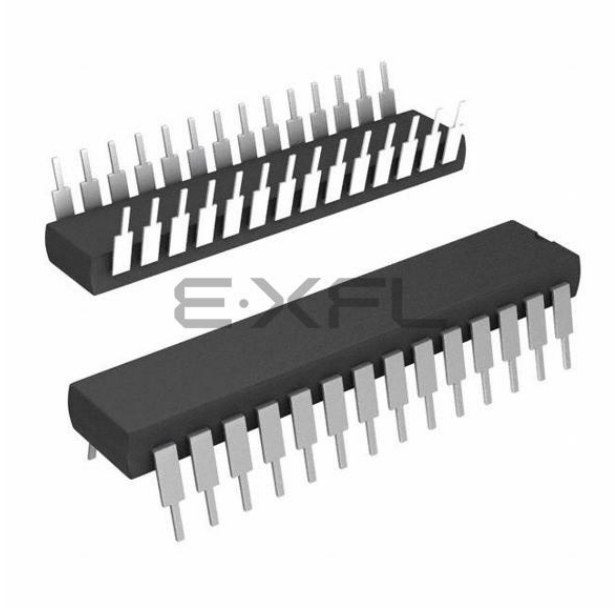

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1716-i-sp

6.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (ECH, ECM, ECL mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (EXTRC) mode circuits.

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators and a dedicated Phase-Lock Loop (HFPLL) that are used to generate three internal system clock sources: the 16 MHz High-Frequency Internal Oscillator (HFINTOSC), 500 kHz (MFINTOSC) and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 6.3 "Clock Switching"** for additional information.

6.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
  - Secondary oscillator during run-time, or
  - An external clock source determined by the value of the FOSC bits.

See **Section 6.3 "Clock Switching"**for more information.

6.2.1.1 EC Mode

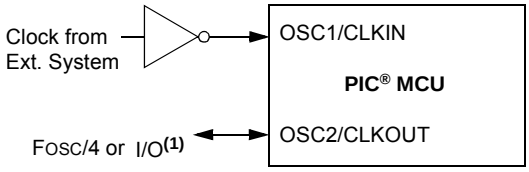
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 6-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Words:

- ECH – High power, 4-32 MHz
- ECM – Medium power, 0.5-4 MHz
- ECL – Low power, 0-0.5 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 6-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

6.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 6-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 6-3 and Figure 6-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

8.3 Register Definitions: Voltage Regulator Control

REGISTER 8-1: VREGCON: VOLTAGE REGULATOR CONTROL REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0	R/W-1/1
—	—	—	—	—	—	VREGPM	Reserved
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **VREGPM:** Voltage Regulator Power Mode Selection bit
- 1 = Low-Power Sleep mode enabled in Sleep(2)
  Draws lowest current in Sleep, slower wake-up
- 0 = Normal-Power mode enabled in Sleep(2)
  Draws higher current in Sleep, faster wake-up

bit 0 **Reserved:** Read as '1'. Maintain this bit set.

Note 1: PIC16F1713/6 only.
2: See **Section 34.0 "Electrical Specifications"**.

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH POWER-DOWN MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	19
VREGCON(1)	—	—	—	—	—	—	VREGPM	Reserved	94
WDTCON	—	—	WDTPS<4:0>					SWDTEN	98

Legend: — = unimplemented location, read as '0'. Shaded cells are not used in Power-Down mode.
Note 1: PIC16F1713/6 only.

EXAMPLE 10-2: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase row is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     PMADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       PMADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       PMADRH
        BCF         PMCON1,CFGS     ; Not configuration space
        BSF         PMCON1,FREE     ; Specify an erase operation
        BSF         PMCON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       PMCON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       PMCON2          ; Write AAh
        BSF         PMCON1,WR       ; Set WR bit to begin erase
        NOP                         ; NOP instructions are forced as processor starts
        NOP                         ; row erase of program memory.
                                    ;
                                    ; The processor stalls until the erase process is complete
                                    ; after erase processor continues with 3rd instruction

        BCF         PMCON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

REGISTER 11-14: ODCONB: PORTB OPEN-DRAIN CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ODB7	ODB6	ODB5	ODB4	ODB3	ODB2	ODB1	ODB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **ODB<7:0>:** PORTB Open-Drain Enable bits
For RB<7:0> pins, respectively
1 = Port pin operates as open-drain drive (sink current only)
0 = Port pin operates as standard push-pull drive (source and sink current)

REGISTER 11-15: SLRCONB: PORTB SLEW RATE CONTROL REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
SLRB7	SLRB6	SLRB5	SLRB4	SLRB3	SLRB2	SLRB1	SLRB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **SLRB<7:0>:** PORTB Slew Rate Enable bits
For RB<7:0> pins, respectively
1 = Port pin slew rate is limited
0 = Port pin slews at maximum rate

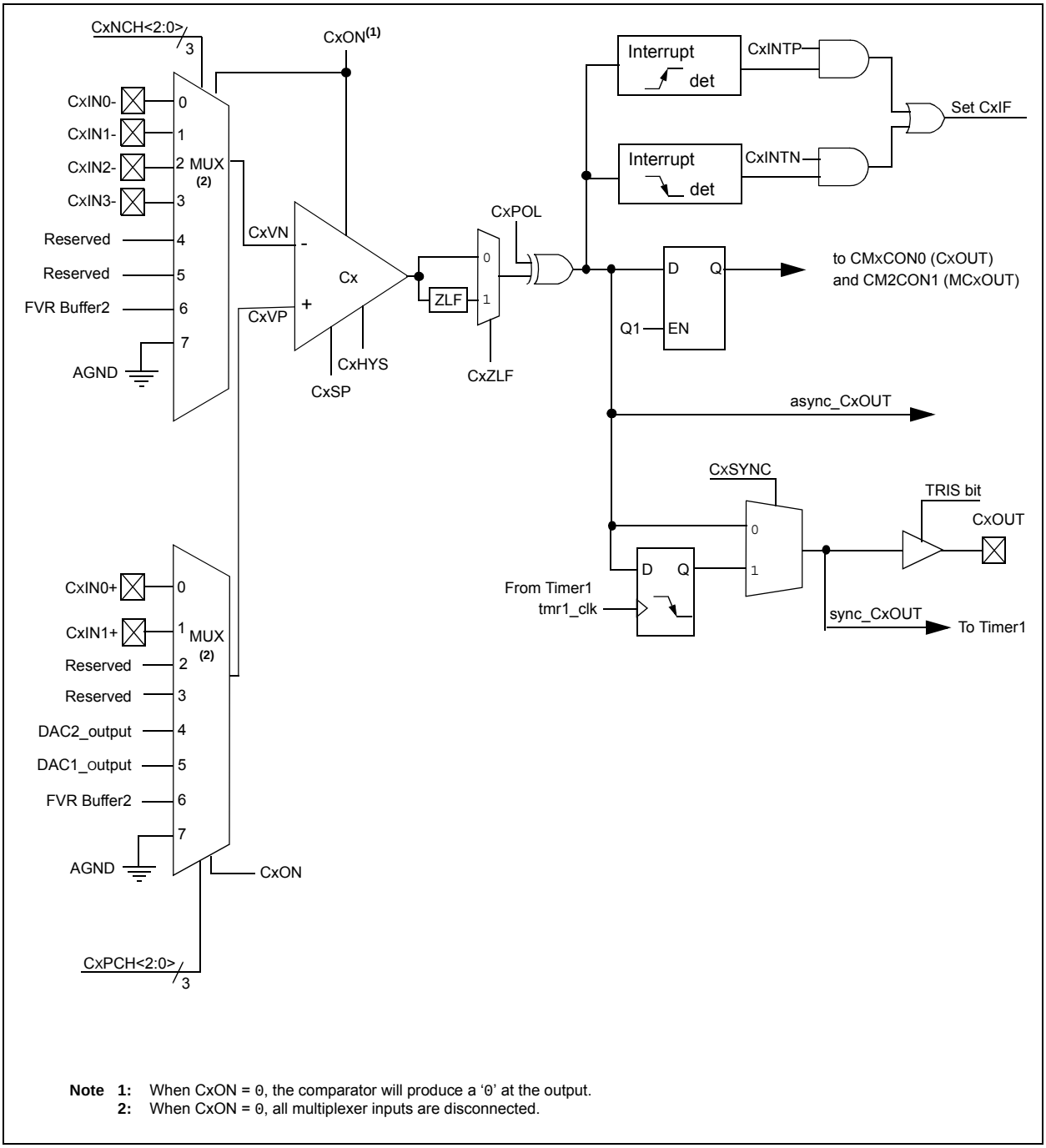
REGISTER 11-16: INLVLB: PORTB INPUT LEVEL CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
INLVLB7	INLVLB6	INLVLB5	INLVLB4	INLVLB3	INLVLB2	INLVLB1	INLVLB0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-0 **INLVLB<7:0>:** PORTB Input Level Select bits
For RB<7:0> pins, respectively
1 = ST input used for PORT reads and interrupt-on-change
0 = TTL input used for PORT reads and interrupt-on-change

FIGURE 16-2: COMPARATOR MODULE SIMPLIFIED BLOCK DIAGRAM



Note 1: When CxON = 0, the comparator will produce a '0' at the output.
2: When CxON = 0, all multiplexer inputs are disconnected.

17.1.9 SETUP FOR PWM OPERATION USING PWMx PINS

The following steps should be taken when configuring the module for PWM operation using the PWMx pins:

1. Disable the PWMx pin output driver(s) by setting the associated TRIS bit(s).
2. Clear the PWMxCON register.
3. Load the PR2 register with the PWM period value.
4. Load the PWMxDCH register and bits <7:6> of the PWMxDCL register with the PWM duty cycle value.
5. Configure and start Timer2:
   - Clear the TMR2IF interrupt flag bit of the PIR1 register. See Note below.
   - Configure the T2CKPS bits of the T2CON register with the Timer2 prescale value.
   - Enable Timer2 by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output pin and wait until Timer2 overflows, TMR2IF bit of the PIR1 register is set. See Note below.
7. Enable the PWMx pin output driver(s) by clearing the associated TRIS bit(s) and setting the desired pin PPS control bits.
8. Configure the PWM module by loading the PWMxCON register with the appropriate values.

Note 1: In order to send a complete duty cycle and period on the first PWM output, the above steps must be followed in the order given. If it is not critical to start with a complete PWM signal, then move Step 8 to replace Step 4.

2: For operation with other peripherals only, disable PWMx pin outputs.

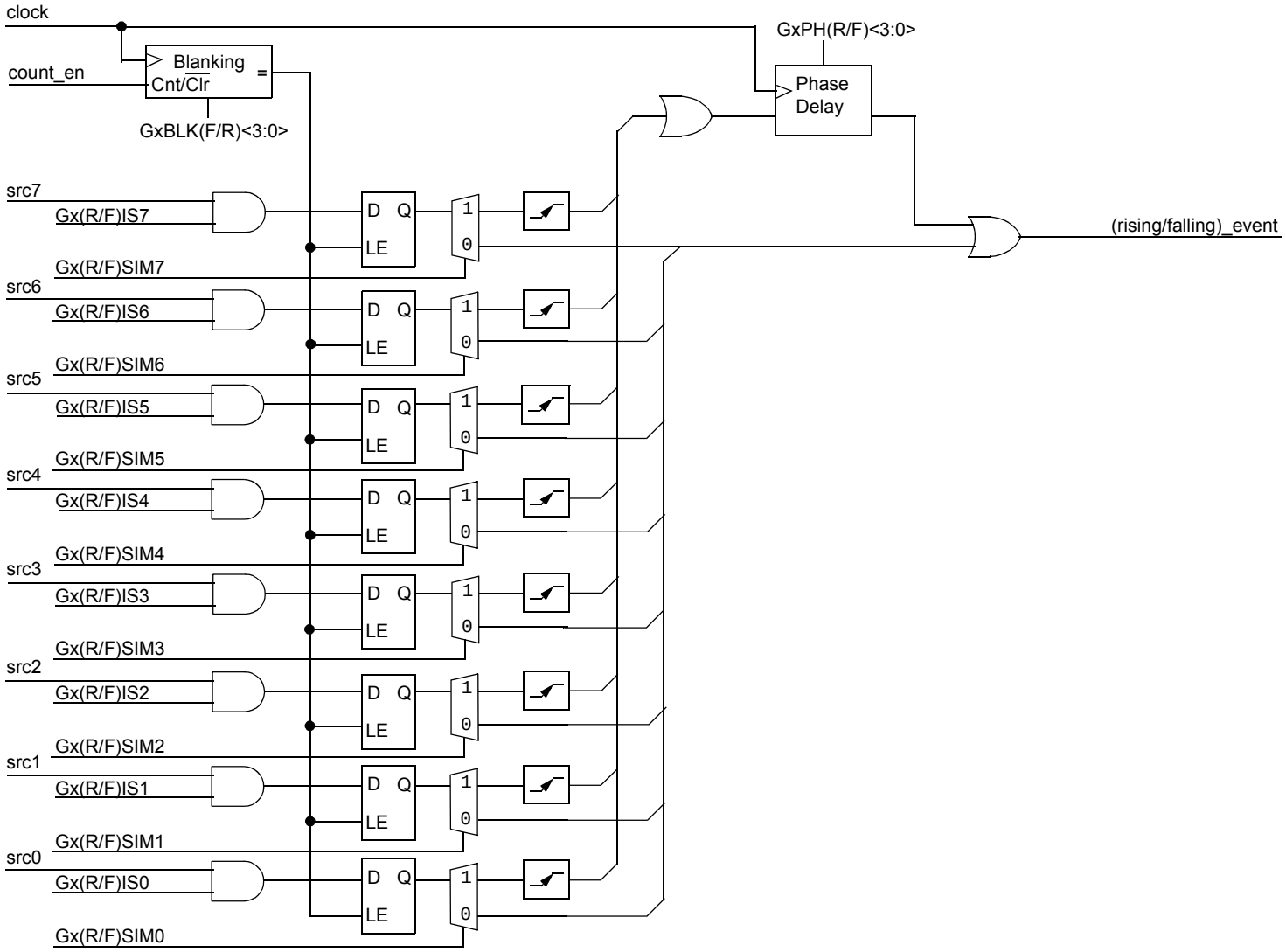
17.1.10 SETUP FOR PWM OPERATION TO OTHER DEVICE PERIPHERALS

The following steps should be taken when configuring the module for PWM operation to be used by other device peripherals:

1. Disable the PWMx pin output driver(s) by setting the associated TRIS bit(s).
2. Clear the PWMxCON register.
3. Load the PR2 register with the PWM period value.
4. Load the PWMxDCH register and bits <7:6> of the PWMxDCL register with the PWM duty cycle value.
5. Configure and start Timer2:
   - Clear the TMR2IF interrupt flag bit of the PIR1 register. See Note below.
   - Configure the T2CKPS bits of the T2CON register with the Timer2 prescale value.
   - Enable Timer2 by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output pin:
   - Wait until Timer2 overflows, TMR2IF bit of the PIR1 register is set. See Note below.
7. Configure the PWM module by loading the PWMxCON register with the appropriate values.

Note: In order to send a complete duty cycle and period on the first PWM output, the above steps must be included in the setup sequence. If it is not critical to start with a complete PWM signal on the first output, then step 6 may be ignored.

FIGURE 18-7: COG (RISING/FALLING) INPUT BLOCK



18.5.4 RISING EVENT DEAD-BAND

Rising event dead band delays the turn-on of the primary outputs from when complementary outputs are turned off. The rising event dead-band time starts when the rising_ event output goes true.

See Section 18.5.1, Asynchronous Delay Chain Dead-band Delay and Section 18.5.2, Synchronous Counter Dead-band Delay for more information on setting the rising edge dead-band time.

18.5.5 FALLING EVENT DEAD-BAND

Falling event dead band delays the turn-on of complementary outputs from when the primary outputs are turned off. The falling event dead-band time starts when the falling_ event output goes true.

See Section 18.5.1, Asynchronous Delay Chain Dead-band Delay and Section 18.5.2, Synchronous Counter Dead-band Delay for more information on setting the rising edge dead-band time.

18.5.6 DEAD-BAND OVERLAP

There are two cases of dead-band overlap:

- Rising-to-falling
- Falling-to-rising

18.5.6.1 Rising-to-Falling Overlap

In this case, the falling event occurs while the rising event dead-band counter is still counting. When this happens, the primary drives are suppressed and the dead-band extends by the falling event dead-band time. At the termination of the extended dead-band time, the complementary drive goes true.

18.5.6.2 Falling-to-Rising Overlap

In this case, the rising event occurs while the falling event dead-band counter is still counting. When this happens, the complementary drive is suppressed and the dead-band extends by the rising event dead-band time. At the termination of the extended dead-band time, the primary drive goes true.

18.6 Blanking Control

Input blanking is a function, whereby, the event inputs can be masked or blanked for a short period of time. This is to prevent electrical transients caused by the turn-on/off of power components from generating a false input event.

The COG contains two blanking counters: one triggered by the rising event and the other triggered by the falling event. The counters are cross coupled with the events they are blanking. The falling event blanking counter is used to blank rising input events and the rising event blanking counter is used to blank falling input events. Once started, blanking extends for the time specified by the corresponding blanking counter.

Blanking is timed by counting COG_clock periods from zero up to the value in the blanking count register. Use Equation 18-1 to calculate blanking times.

18.6.1 FALLING EVENT BLANKING OF RISING EVENT INPUTS

The falling event blanking counter inhibits rising event inputs from triggering a rising event. The falling event blanking time starts when the rising event output drive goes false.

The falling event blanking time is set by the value contained in the COGxBLKF register (Register 18-13). Blanking times are calculated using the formula shown in Equation 18-1.

When the COGxBLKF value is zero, falling event blanking is disabled and the blanking counter output is true, thereby, allowing the event signal to pass straight through to the event trigger circuit.

18.6.2 RISING EVENT BLANKING OF FALLING EVENT INPUTS

The rising event blanking counter inhibits falling event inputs from triggering a falling event. The rising event blanking time starts when the falling event output drive goes false.

The rising event blanking time is set by the value contained in the COGxBLKR register (Register 18-12).

When the COGxBLKR value is zero, rising event blanking is disabled and the blanking counter output is true, thereby, allowing the event signal to pass straight through to the event trigger circuit.

18.6.3 BLANKING TIME UNCERTAINTY

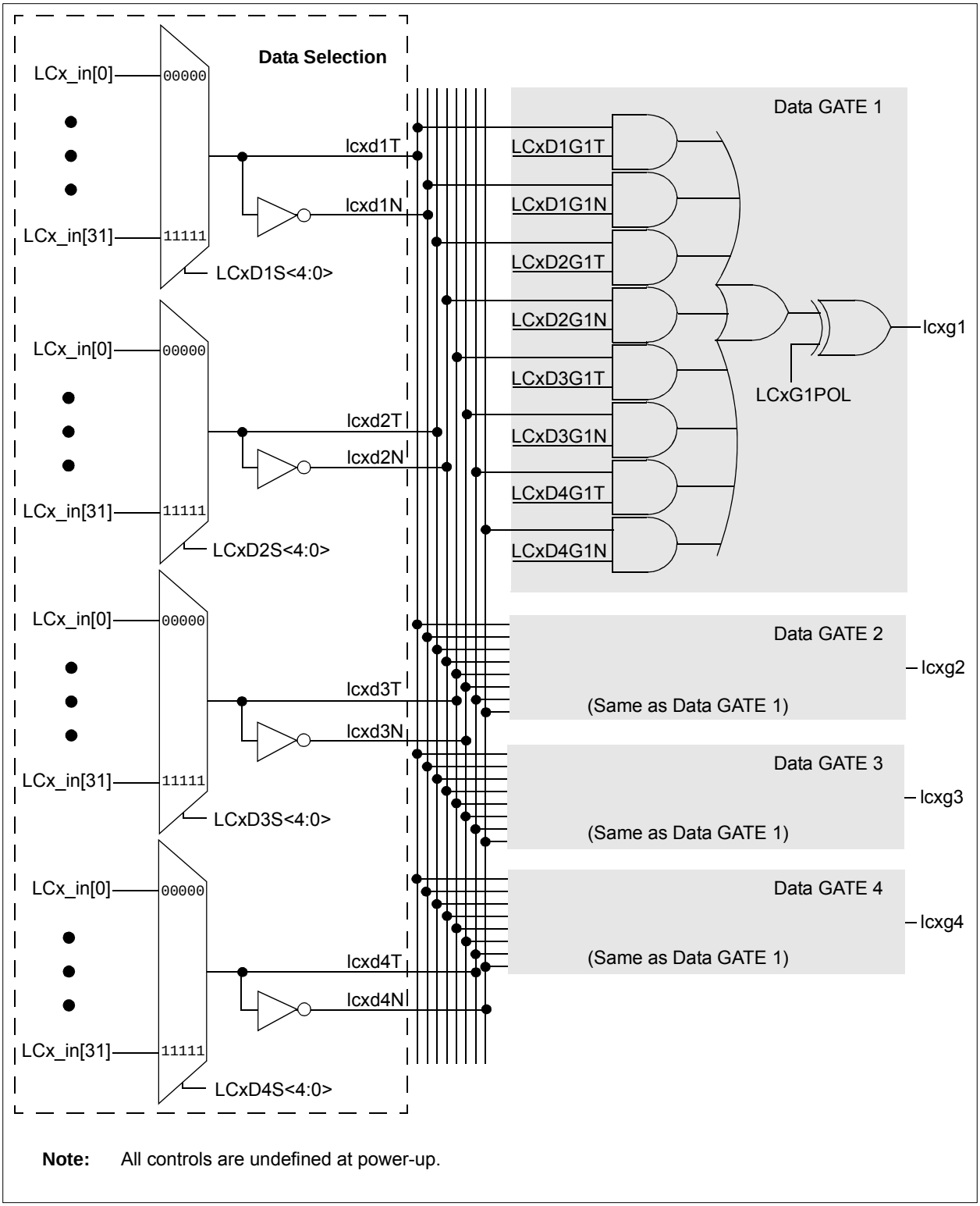
When the rising and falling sources that trigger the blanking counters are asynchronous to the COG_clock, it creates uncertainty in the blanking time. The maximum uncertainty is equal to one COG_clock period. Refer to Equation 18-1 and Example 18-1 for more detail.

18.7 Phase Delay

It is possible to delay the assertion of either or both the rising event and falling events. This is accomplished by placing a non-zero value in COGxPHR or COGxPHF phase-delay count register, respectively (Register 18-14 and Register 18-15). Refer to Figure 18-10 for COG operation with CCP1 and phase delay. The delay from the input rising event signal switching to the actual assertion of the events is calculated the same as the dead-band and blanking delays. Refer to Equation 18-1.

When the phase-delay count value is zero, phase delay is disabled and the phase-delay counter output is true, thereby, allowing the event signal to pass straight through to the complementary output driver flop.

FIGURE 19-2: INPUT DATA SELECTION AND GATING



Note: All controls are undefined at power-up.

REGISTER 20-3: NCOxACCL: NCOx ACCUMULATOR REGISTER – LOW BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
NCOxACC<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **NCOxACC<7:0>:** NCOx Accumulator, Low Byte

REGISTER 20-4: NCOxACCH: NCOx ACCUMULATOR REGISTER – HIGH BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
NCOxACC<15:8>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **NCOxACC<15:8>:** NCOx Accumulator, High Byte

REGISTER 20-5: NCOxACCU: NCOx ACCUMULATOR REGISTER – UPPER BYTE

U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	NCOxACC<19:16>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **NCOxACC<19:16>:** NCOx Accumulator, Upper Byte

22.3 Register Definitions: Op Amp Control

REGISTER 22-1: OPAxCON: OPERATIONAL AMPLIFIERS (OPAx) CONTROL REGISTERS

R/W-0/0	R/W-0/0	U-0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
OPAxEN	OPAxSP	—	OPAxUG	—	—	OPAxCH<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **OPAxEN:** Op Amp Enable bit
1 = Op amp is enabled
0 = Op amp is disabled and consumes no active power

bit 6 **OPAxSP:** Op Amp Speed/Power Select bit
1 = Op amp operates in high GBWP mode
0 = Reserved. D not use.

bit 5 **Unimplemented:** Read as '0'

bit 4 **OPAxUG:** Op Amp Unity Gain Select bit
1 = OPA output is connected to inverting input. OPAxIN- pin is available for general purpose I/O.
0 = Inverting input is connected to the OPAxIN- pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **OPAxCH<1:0>:** Non-inverting Channel Selection bits
11 = Non-inverting input connects to FVR Buffer 2 output
10 = Non-inverting input connects to DAC1_output
01 = Non-inverting input connects to DAC2_output
00 = Non-inverting input connects to OPAxIN+ pin

TABLE 22-1: SUMMARY OF REGISTERS ASSOCIATED WITH OP AMPS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	—	—	ANSA	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	120
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	126
DAC1CON0	DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS	249
DAC1CON1	DAC1R<7:0>								249
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		151
OPA1CON	OPA1EN	OPA1SP	—	OPA1UG	—	—	OPA1PCH<1:0>		245
OPA2CON	OPA2EN	OPA2SP	—	OPA2UG	—	—	OPA2PCH<1:0>		245
TRISA	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	119
TRISB	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	125

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by op amps.

23.6 Register Definitions: DAC Control

REGISTER 23-1: DAC1CON0: VOLTAGE REFERENCE CONTROL REGISTER 0

R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0
DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **DAC1EN:** DAC1 Enable bit
1 = DAC is enabled
0 = DAC is disabled

bit 6 **Unimplemented:** Read as ‘0’

bit 5 **DAC1OE1:** DAC1 Voltage Output 1 Enable bit
1 = DAC voltage level is also an output on the DAC1OUT1 pin
0 = DAC voltage level is disconnected from the DAC1OUT1 pin

bit 4 **DAC1OE2:** DAC1 Voltage Output 2 Enable bit
1 = DAC voltage level is also an output on the DAC1OUT2 pin
0 = DAC voltage level is disconnected from the DAC1OUT2 pin

bit 3-2 **DAC1PSS<1:0>:** DAC1 Positive Source Select bits
11 = Reserved, do not use
10 = FVR Buffer2 output
01 = V_{REF+} pin
00 = V_{DD}

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **DAC1NSS:** DAC1 Negative Source Select bits
1 = V_{REF-} pin
0 = V_{SS}

REGISTER 23-2: DAC1CON1: VOLTAGE REFERENCE CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
DAC1R<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **DAC1R<7:0>:** DAC1 Voltage Output Select bits

TABLE 23-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE DAC1 MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
DAC1CON0	DAC1EN	—	DAC1OE1	DAC1OE2	DAC1PSS<1:0>		—	DAC1NSS	249
DAC1CON1	DAC1R<7:0>								249

Legend: — = Unimplemented location, read as ‘0’. Shaded cells are not used with the DAC module.

26.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

26.4 Timer1 (Secondary) Oscillator

A dedicated low-power 32.768 kHz oscillator circuit is built-in between pins SOSCI (input) and SOSCO (amplifier output). This internal circuit is to be used in conjunction with an external 32.768 kHz crystal.

The oscillator circuit is enabled by setting the T1OSCEN bit of the T1CON register. The oscillator will continue to run during Sleep.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to using Timer1. A suitable delay similar to the OST delay can be implemented in software by clearing the TMR1IF bit then presetting the TMR1H:TMR1L register pair to FC00h. The TMR1IF flag will be set when 1024 clock cycles have elapsed, thereby indicating that the oscillator is running and reasonably stable.

26.5 Timer1 Operation in Asynchronous Counter Mode

If the control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer increments asynchronously to the internal phase clocks. If the external clock source is selected then the timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 26.5.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce an additional increment.

26.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TMR1L register pair.

26.6 Timer1 Gate

Timer1 can be configured to count freely or the count can be enabled and disabled using Timer1 gate circuitry. This is also referred to as Timer1 Gate Enable.

Timer1 gate can also be driven by multiple selectable sources.

26.6.1 TIMER1 GATE ENABLE

The Timer1 Gate Enable mode is enabled by setting the TMR1GE bit of the T1GCON register. The polarity of the Timer1 Gate Enable mode is configured using the T1GPOL bit of the T1GCON register.

When Timer1 Gate Enable mode is enabled, Timer1 will increment on the rising edge of the Timer1 clock source. When Timer1 Gate Enable mode is disabled, no incrementing will occur and Timer1 will hold the current count. See Figure 26-3 for timing details.

TABLE 26-3: TIMER1 GATE ENABLE SELECTIONS

T1CLK	T1GPOL	T1G	Timer1 Operation
↑	0	0	Counts
↑	0	1	Holds Count
↑	1	0	Holds Count
↑	1	1	Counts

28.9 Register Definitions: ZCD Control

REGISTER 28-1: ZCDxCON: ZERO-CROSS DETECTION CONTROL REGISTER

R/W-0/0	U-0	R-x/x	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
ZCDxEN	—	ZCDxOUT	ZCDxPOL	—	—	ZCDxINTP	ZCDxINTN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = value depends on configuration bits

bit 7 **ZCDxEN:** Zero-Cross Detection Enable bit(1)
- 1 = Zero-cross detect is enabled. ZCD pin is forced to output to source and sink current.
- 0 = Zero-cross detect is disabled. ZCD pin operates according to PPS and TRIS controls.

bit 6 **Unimplemented:** Read as '0'

bit 5 **ZCDxOUT:** Zero-Cross Detection Logic Level bit

ZCDxPOL bit = 0:
- 1 = ZCD pin is sinking current
- 0 = ZCD pin is sourcing current

ZCDxPOL bit = 1:
- 1 = ZCD pin is sourcing current
- 0 = ZCD pin is sinking current

bit 4 **ZCDxPOL:** Zero-Cross Detection Logic Output Polarity bit
- 1 = ZCD logic output is inverted
- 0 = ZCD logic output is not inverted

bit 3-2 **Unimplemented:** Read as '0'

bit 1 **ZCDxINTP:** Zero-Cross Positive Edge Interrupt Enable bit
- 1 = ZCDIF bit is set on low-to-high ZCDx_output transition
- 0 = ZCDIF bit is unaffected by low-to-high ZCDx_output transition

bit 0 **ZCDxINTN:** Zero-Cross Negative Edge Interrupt Enable bit
- 1 = ZCDIF bit is set on high-to-low ZCDx_output transition
- 0 = ZCDIF bit is unaffected by high-to-low ZCDx_output transition

Note 1: The ZCDxEN bit has no effect when the ZCDDIS Configuration bit is cleared.

TABLE 28-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE ZCD MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
PIE3	—	—	COGIE	ZCDIE	—	—	—	—	86
PIR3	—	—	CWGIF	ZCDIF	—	—	—	—	89
ZCD1CON	ZCD1EN	—	ZCD1OUT	ZCD1POL	—	—	ZCD1INTP	ZCD1INTN	276

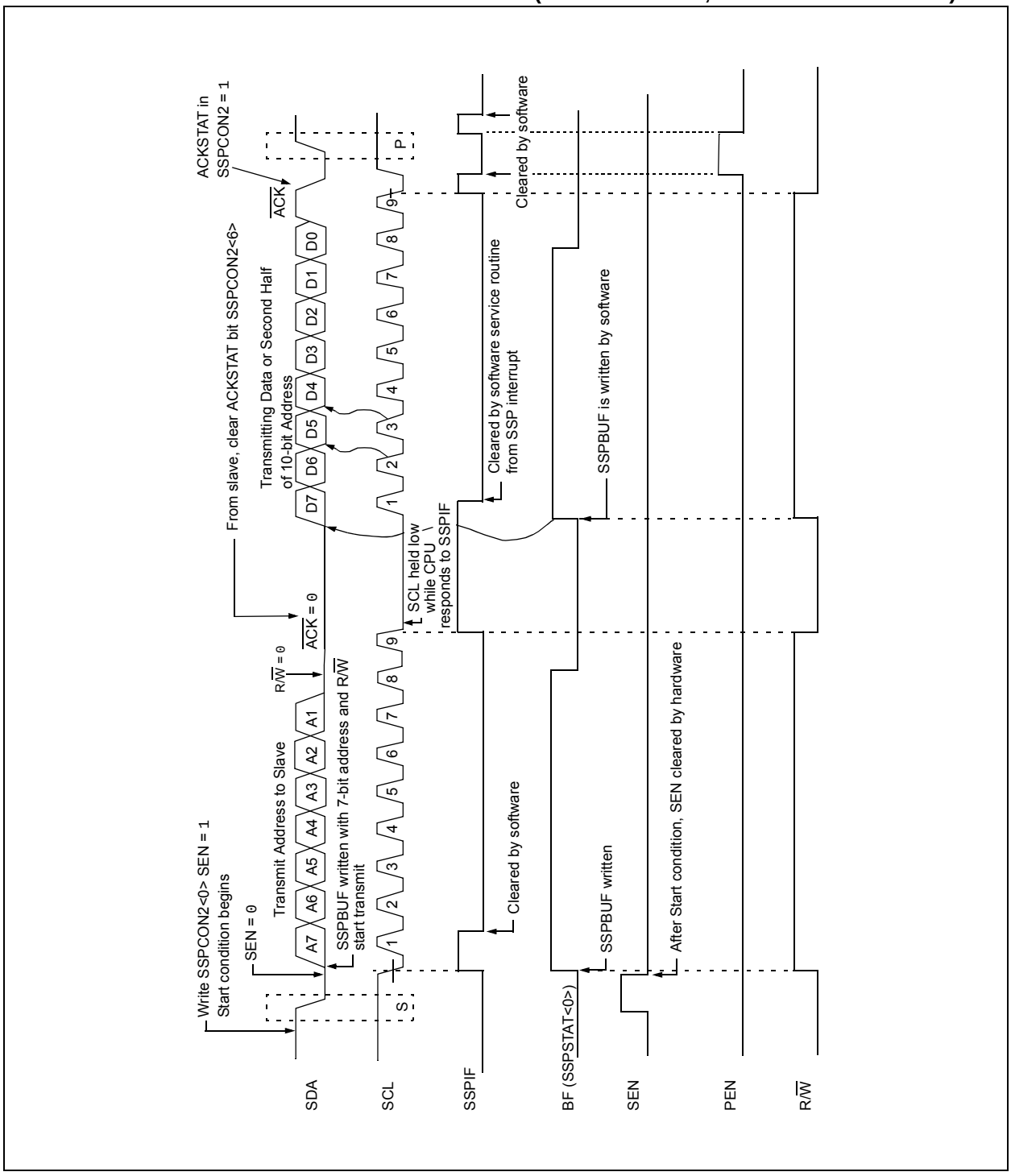
Legend: — = unimplemented, read as '0'. Shaded cells are unused by the ZCD module.

TABLE 28-2: SUMMARY OF CONFIGURATION WORD WITH THE ZCD MODULE

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG2	13:8	—	—	LVP	$\overline{\text{DEBUG}}$	$\overline{\text{LPBOR}}$	BORV	STVREN	PLLEN	49
	7:0	ZCDDIS	—	—	—	—	—	WRT<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the ZCD module.

FIGURE 30-28: I²C MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



34.3 DC Characteristics

TABLE 34-1: SUPPLY VOLTAGE

PIC16LF1713/6			Standard Operating Conditions (unless otherwise stated)				
PIC16F1713/6							
Param. No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD	**Supply Voltage**					
			VDDMIN 1.8 2.5	 — —	VDDMAX 3.6 3.6	 V V	 FOSC ≤ 16 MHz FOSC > 16 MHz (**Note 2**)
D001			2.3 2.5	— —	5.5 5.5	V V	FOSC ≤ 16 MHz: FOSC > 16 MHz (**Note 2**)
D002*	VDR	**RAM Data Retention Voltage(1)**					
			1.5	—	—	V	Device in Sleep mode
D002*			1.7	—	—	V	Device in Sleep mode
D002A*	VPOR	**Power-on Reset Release Voltage(3)**					
			—	1.6	—	V	
D002A*			—	1.6	—	V	
D002B*	VPORR*	**Power-on Reset Rearm Voltage(3)**					
			—	0.8	—	V	
D002B*			—	1.5	—	V	
D003	VFVR	**Fixed Voltage Reference Voltage(4)**	-4	—	+4	%	1x Gain, 1.024, VDD ≥ 2.5V, -40°C to 85°C
			-4	—	+4	%	2x Gain, 2.048, VDD ≥ 2.5V, -40°C to 85°C
			-5	—	+5	%	4x Gain, 4.096, VDD ≥ 4.75V, -40°C to 85°C
D004*	SVDD	**VDD Rise Rate**	0.05	—	—	V/ms	Ensures that the Power-on Reset signal is released properly.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

3: See Figure 34-3: POR and POR Rearm with Slow Rising VDD.

4: Industrial temperature range only.

TABLE 34-15: ANALOG-TO-DIGITAL CONVERTER (ADC) CHARACTERISTICS(1,2,3,4):

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C, Single-ended, 2 μs TAD, VREF+ = 3V, VREF- = VSS							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10	bit	
AD02	EIL	Integral Error	—	—	±1.7	LSb	VREF = 3.0V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes, VREF = 3.0V
AD04	EOFF	Offset Error	—	—	±2.5	LSb	VREF = 3.0V
AD05	EGN	Gain Error	—	—	±2.0	LSb	VREF = 3.0V
AD06	VREF	Reference Voltage	1.8	—	VDD	V	VREF = (VREF+ minus VREF-)
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	Can go higher if external 0.01 μF capacitor is present on input pin.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The ADC conversion result never decreases with an increase in the input voltage and has no missing codes.

3: ADC VREF is from external VREF+ pin, VDD pin or FVR, whichever is selected as reference input.

4: See **Section 35.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

TABLE 34-16: ADC CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	ADC Clock Period (TADC)	1.0	—	9.0	μs	FOSC-based
		ADC Internal FRC Oscillator Period (TFRC)	1.0	2	6.0	μs	ADCS<1:0> = 11 (ADC FRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	5.0	—	μs	
AD133*	THCD	Holding Capacitor Disconnect Time	—	1/2 TAD	—		ADCS<2:0> ≠ x11 (FOSC based)
			—	1/2 TAD + 1TCY	—		ADCS<2:0> = x11 (FRC based)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The ADRES register may be read on the following TCY cycle.

FIGURE 34-19: SPI SLAVE MODE TIMING (CKE = 0)

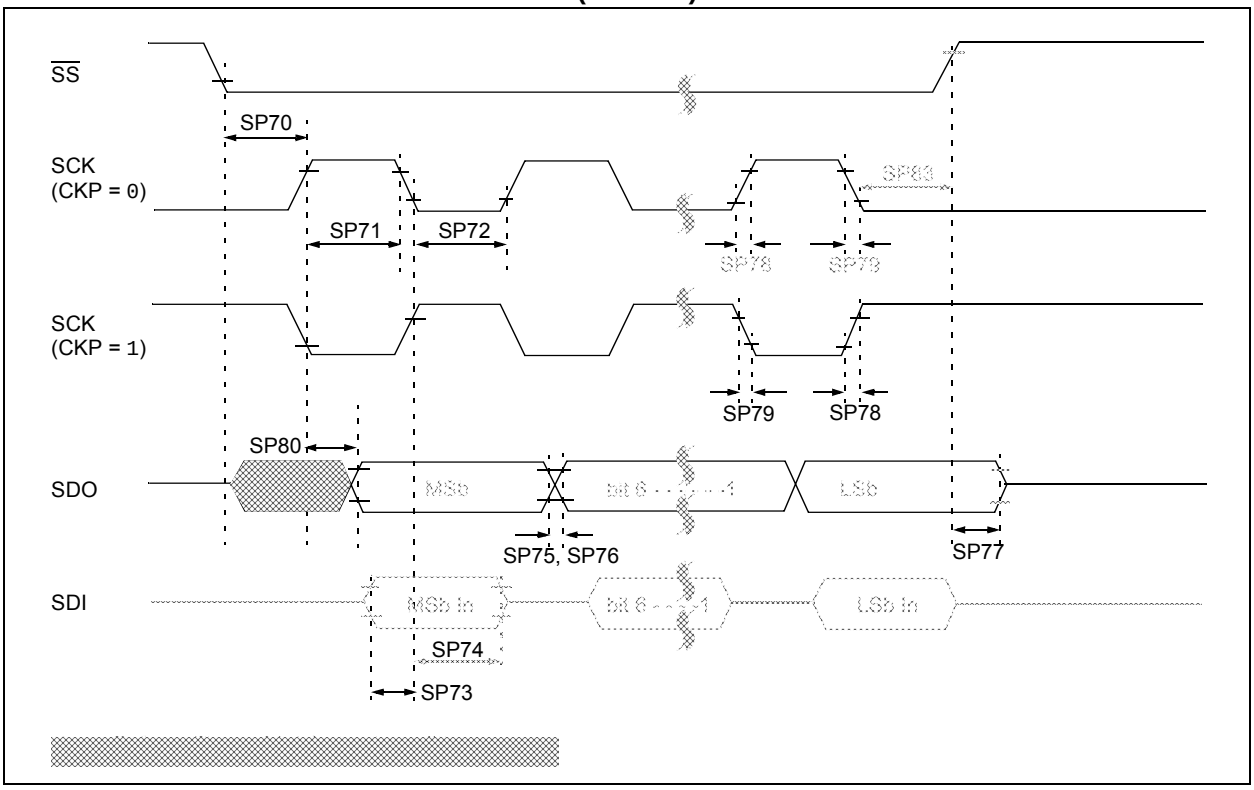
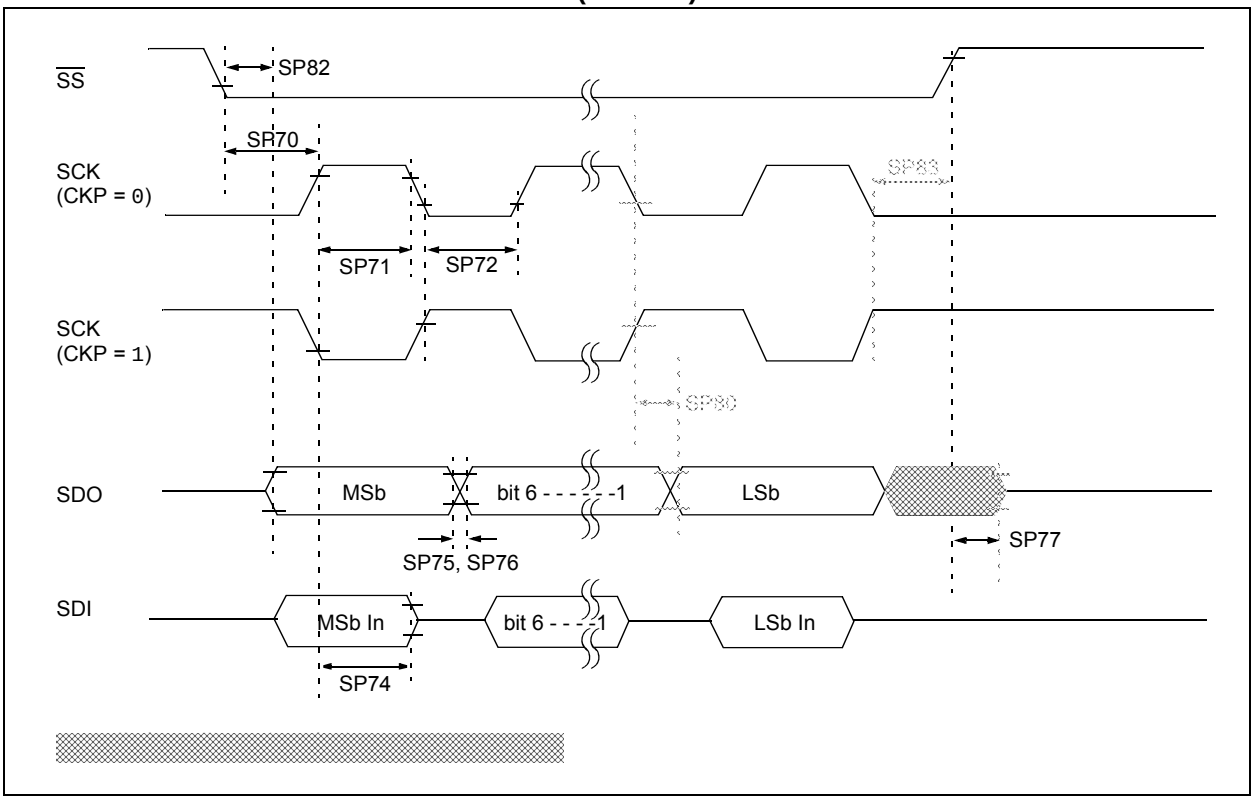


FIGURE 34-20: SPI SLAVE MODE TIMING (CKE = 1)



Note: Unless otherwise noted, VIN = 5V, FOSC = 300 kHz, CIN = 0.1 µF, TA = 25°C.

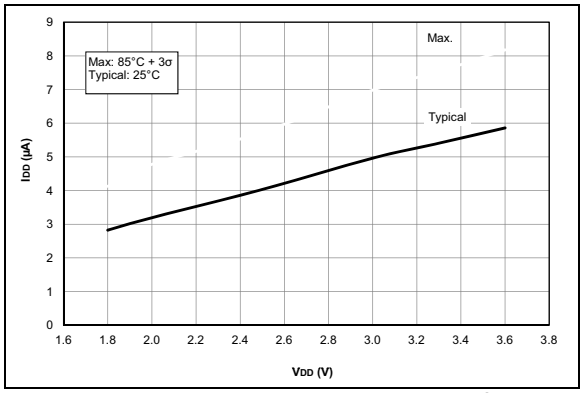


FIGURE 35-19: *IDD, LFINTOSC Mode, Fosc = 31 kHz, PIC16LF1713/6 Only.*

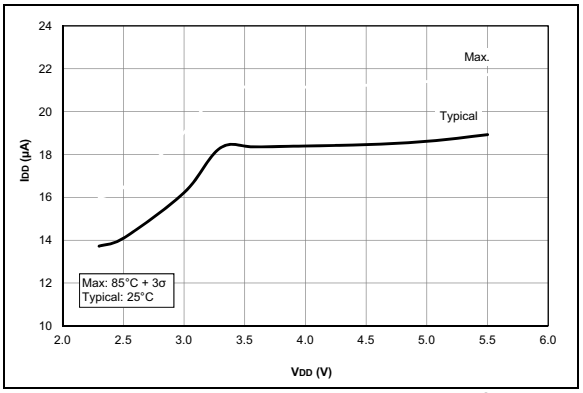


FIGURE 35-20: *IDD, LFINTOSC Mode, Fosc = 31 kHz, PIC16F1713/6 Only.*

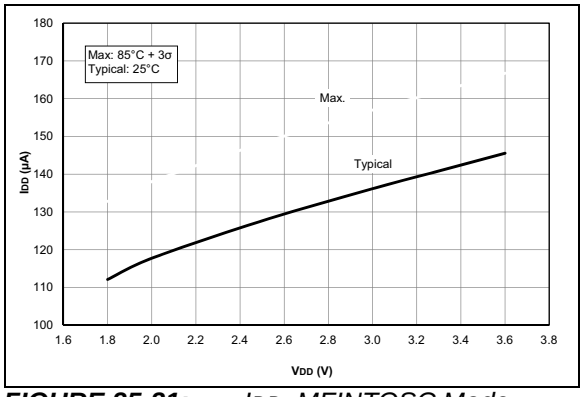


FIGURE 35-21: *IDD, MFINTOSC Mode, Fosc = 500 kHz, PIC16LF1713/6 Only.*

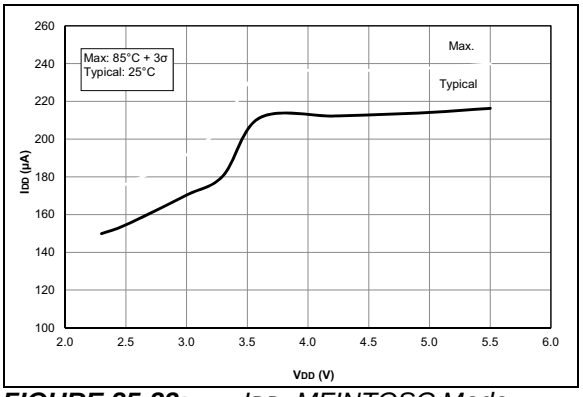


FIGURE 35-22: *IDD, MFINTOSC Mode, Fosc = 500 kHz, PIC16F1713/6 Only.*

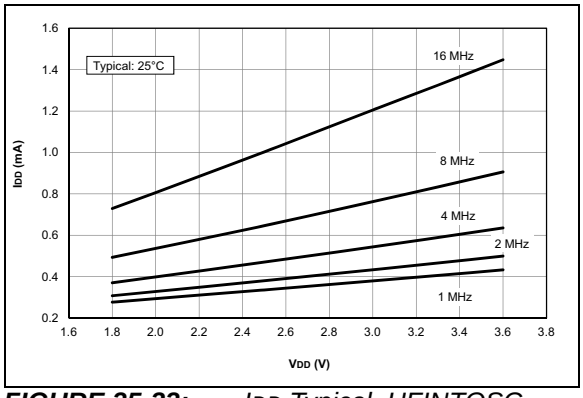


FIGURE 35-23: *IDD Typical, HFINTOSC Mode, PIC16LF1713/6 Only.*

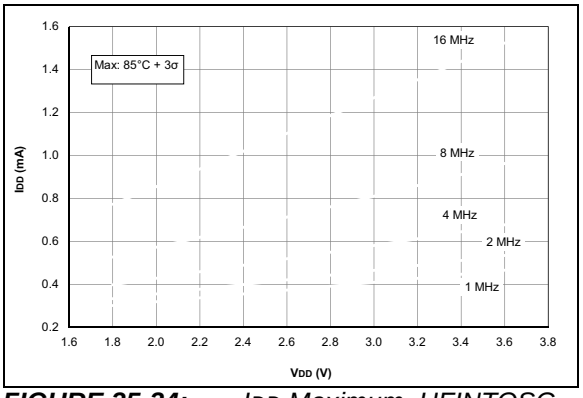


FIGURE 35-24: *IDD Maximum, HFINTOSC Mode, PIC16LF1713/6 Only.*

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ISBN: 978-1-5224-0172-8

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